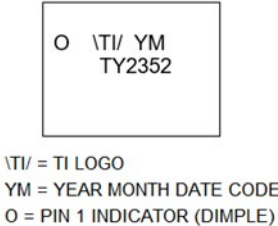
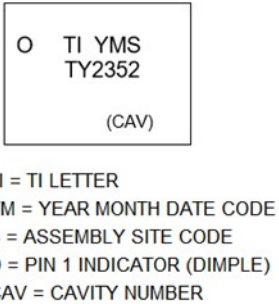


PCN Number:	20240202009.1		PCN Date:	February 02, 2024																			
Title:	Qualification of RFAB as an additional Fab site option, Die Revision, and BOM Option for select devices																						
Customer Contact:	Change Management Team		Dept:	Quality Services																			
Proposed 1st Ship Date:	May 2, 2024		Sample requests accepted until:	Mar 2, 2024*																			
*Sample requests received after March 2, 2024 will not be supported.																							
Change Type:																							
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material																		
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site																		
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material																		
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process																		
PCN Details																							
Description of Change:																							
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option in addition to a BOM option for the devices listed below.																							
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>DL-LIN</td> <td>LINCMOS</td> <td>150 mm</td> <td>RFAB</td> <td>LBC9</td> <td>300 mm</td> </tr> </tbody> </table>			Current Fab Site			Additional Fab Site			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	DL-LIN	LINCMOS	150 mm	RFAB	LBC9	300 mm			
Current Fab Site			Additional Fab Site																				
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																		
DL-LIN	LINCMOS	150 mm	RFAB	LBC9	300 mm																		
The die was also changed as a result of the process change.																							
Additional BOM items are as follows:																							
		Current	Proposed																				
Die Thickness		10.5 mil	7.5 mil																				
Wire diam		0.96mil	0.80mil																				
Package marking change:																							
Package Marking (Sample)	Current		Proposed																				
																							
Qual details are provided in the Qual Data Section.																							
Reason for Change:																							
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.																							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																							
None																							
Impact on Environmental Ratings																							

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS

☒ No Change

REACH

☒ No Change

Green Status

☒ No Change

IEC 62474

☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
RFAB	RFB	USA	Richardson

Die Rev:

Current

New

Die Rev [2P]	Die Rev [2P]
E, C	A

Sample product shipping label (not actual product label):



Product Affected:

TLC352IPWR	TLC372CPWR	TLV2352IPWR
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For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLC352IPWR	QBS Reference: LM2902BQPWRQ1	QBS Reference: TPS43000PW	QBS Reference: SN74LV8T245QPWRQ1	QBS Reference: TPS71559DCKRM3	QBS Reference: LM2901BQPWRQ1	QBS Reference: PSN2012025A12AACJR	QBS Reference: PSN2012025A12CACJR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	1/77/0	-	1/77/0	-	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	3/231/0	-	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	-	1/77/0	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	-	-	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0	-	1/77/1	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	-	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0	-	1/77/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231	-	2/154/0	1/77/0
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0	-	-	-	-
HTOL	B1	Life Test	150C	408 Hours	-	3/231/0	-	-	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device TLC352IPWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2310-049

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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